



Product Data Sheet

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PRODUCT #: N9930

TIDY SUMP

Equipment Cleaner

DESCRIPTION: A liquid concentrate designed to clean and condition developing and resist stripping machines, and other equipment. **TIDY SUMP** will remove a variety of contaminants such as residues from dry film photoresists, solder masks, and antifoams. A regular maintenance program using **TIDY SUMP** will insure maximum efficiency from equipment, consistent high quality product and minimum down-time.

BENEFITS:

- **Fast-acting on deposits**
- **Lower maintenance saves hours of down-time**
- **Helps remove antifoam residues**

SPECIFICATIONS:

Density:	1.23 gm/ml, 10.2 lbs./gal.
pH at 10% :	11.2
Flash Point (TCC):	None
Shelf life:	Indefinite

INSTRUCTIONS: **TIDY SUMP** should be used regularly for maximum effectiveness. Fill machine sump to normal working level or slightly above. Allow the solution to circulate in the machine for approximately 90 minutes at 100°-120°F. The degree of contamination will determine the time and temperature necessary to clean the equipment. Drain solution and rinse. **TIDY SUMP** is compatible with resist stripping and developing solutions, so it is usually not necessary to neutralize after cleaning. If an acid rinse is desired, it should be done after treatment with **TIDY SUMP**.

Developers:

Use at 10% for initial cleanout and discard. For subsequent cleanout, use at 5% for once per month cleanout; 2%-3% for biweekly cleanout.

Liquid photoimageable/dry film solder mask developers:

Use at 100°-140°F, 10%-12% for initial cleanout; 5% for biweekly cleanout.

Resist strippers:

Use at 10% for initial cleanout and discard. Make up at 3% for subsequent use. Clean out machine once per month.

CAUTIONS: **TIDY SUMP** is alkaline; avoid contact with skin and eyes. Goggles or glasses and gloves should be worn when handling this product. In case of contact with eyes, flush with water for at least 15 minutes and obtain medical assistance. For skin contact, rinse immediately with water. Refer to Material Safety Data Sheet for further information.

DISPOSAL: Refer to waste treatment information on the reverse side.

***TIDY SUMP* Waste Treatment**

The following general information is provided for the waste treatment of ***TIDY SUMP***. This information should answer most questions regarding waste treatment of spent solutions of this product.

Before waste treating a spent solution, it is important to determine if the solution needs to be treated and which materials you are treating for. The following information should help make that determination.

TIDY SUMP contains a metal chelating agent; therefore, it should be segregated from waste streams found to be incompatible with metal chelating agents. ***TIDY SUMP*** should be treated in a tank or container into which the solution is pumped; it should not be treated in the sump of the machine.

Our analysis of spent ***TIDY SUMP*** indicates that it contains suspended film residue, ink solids, and metals within the following ranges:

Typical Spent *TIDY SUMP*

15-40 PPM Copper
20-50 PPM Lead
10-30 PPM Tin
0.3-0.5% Solids

Procedure for Batch Treatment of *TIDY SUMP*

Removal of Solids*

1. Lower pH of spent solution to 3.0 with 10-20% sulfuric acid.
2. Allow to settle; decant solution.

Removal of Metals and Solids*

1. Lower pH of spent solution to 3.0 with 10-20% sulfuric acid.
2. Add, with mixing, approximately 75 grams per gallon of ***METALTREAT 5000*** (sodium dimethyldithiocarbamate) to the solution.
3. Allow to settle; decant solution.

* A large amount of flocculant from the product may precipitate out if the pH drops below 3.0.

This product should be used only for its intended purpose. The information stated above is based on our laboratory tests and experience, and is accurate to the best of our knowledge. Since actual use is beyond our control, the recommendations or suggestions are made without warranty, expressed or implied.